

Notice of References Cited	Application/Control No. 10/791,696	Applicant(s)/Patent Under Reexamination LEE ET AL.	
	Examiner Joanne H. Kim	Art Unit 2883	Page 1 of 1

U.S. PATENT DOCUMENTS

*		Document Number Country Code-Number-Kind Code	Date MM-YYYY	Name	Classification
	A	US-2003/0021551	01-2003	Carpenter et al.	385/89
	B	US-6,792,182	09-2004	Davies et al.	385/37
	C	US-2003/0161576	08-2003	Blair et al.	385/18
	D	US-2002/0074086	06-2002	Nakamura et al.	156/329
	E	US-2004/0190111	09-2004	Callies et al.	359/291
	F	US-5,991,493	11-1999	Dawes et al.	385/141
	G	US-6,363,183	03-2002	Koh, Seungug	385/19
	H	US-6,636,652	10-2003	Kopelman et al.	385/12
	I	US-2002/0005976	01-2002	Behin et al.	359/254
	J	US-2004/0057877	03-2004	Rarbach et al.	422/101
	K	US-			
	L	US-			
	M	US-			

FOREIGN PATENT DOCUMENTS

*		Document Number Country Code-Number-Kind Code	Date MM-YYYY	Country	Name	Classification
	N					
	O					
	P					
	Q					
	R					
	S					
	T					

NON-PATENT DOCUMENTS

*		Include as applicable: Author, Title Date, Publisher, Edition or Volume, Pertinent Pages)
	U	Cheng et al., "A Hermetic Glass-Silicon Package Formed Using Localized Aluminum/Silicon-Glass Bonding," September 2001, Journal of Microelectromechanical systems, vol.10, No.3
	V	
	W	
	X	

*A copy of this reference is not being furnished with this Office action. (See MPEP § 707.05(a).)
Dates in MM-YYYY format are publication dates. Classifications may be US or foreign.